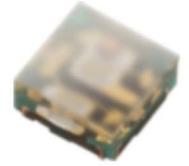


DATASHEET

SMD • 18-038T/ BDGAR6S1-S06/10T(LT)



Features

- Package in 8mm tape on 7["] diameter reel
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow
- Solder process
- Full-color type
- Pb-free
- Component solderable surface finish is Gold
- Component weight is 1.0 mg
- RoHS compliant

Description

• The 18-038T SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

• Moreover, with its black PCB, the 18-038T possess an ideal solution for high-contract and high-resolution indoor signage display.

Applications

- Indoor signage display applications
- Indoor decorating and entertainment design
- Flat backlight for LCD, switch and symbol
- Indicator and backlighting for all consumer electronics

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Red	
InGaN	Brilliant Green	Surface Diffused
InGaN	Brilliant Blue	

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V _R	5	V	
Forward Current	lF	R6:10 GA:10 BD:10	mA	
Peak Forward Current (Duty 1/10 @1KHz)	IFP	R6:20 GA:20 BD:20	mA	
Power Dissipation	Pd	R6:24 GA:35 BD:35	mW	
Junction Temperature	Т _ј	100	°C	
Operating Temperature	T _{opr}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +90	Ĵ	
ESD (Classification acc. AEC Q101)	ESD _{HBM}	R:2000 G:1000 B:1000	V	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 $^\circ\!\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^\circ\!\mathbb{C}$ for 3 sec.		

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol		Min.	Тур.	Max.	Unit	Condition
		R6	37.0		94.0		
Luminous Intensity	lv	GA	120.0		300.0	mcd	I _F =10mA
		BD	20.0		60.0		
Viewing Angle	20 _{1/2}			120		deg	I _F =10mA
		R6		632			
Peak Wavelength	Λр	GA		518		nm	I _F =10mA
		BD		468			
		R6	618.0		630.0		
Dominant Wavelength	Λd	GA	513.0		531.0	nm	I _F =10mA
		BD	461.0		476.0		
Spectrum Dediction		R6		20			
Spectrum Radiation	Δλ	GA		25		nm	I _F =10mA
Bandwidth		BD		25			
		R6	1.7	2.0	2.35		
Forward Voltage	V_{F}	GA	2.5	3.3	3.7	V	I _F =10mA
-		BD	2.5	3.3	3.7		
Reverse Current	I _R				10	μA	V _R =5V

Note:

1. Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

Floating Bin(R6) Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
RA	37	45		
RB	45	54	_	
RC	54	65	mcd	I _F =10mA
RD	65	78	_	
RE	78	94	_	

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
R1	618.0	621.0		
R2	621.0	624.0	-	I _F =10mA
R3	624.0	627.0	nm	
R4	627.0	630.0		

Bin Range of Dominant Voltage

Bin Code	Min.	Max.	Unit	Condition
R1	1.7	2.35	V	I _F =10mA

Note:

1. Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

Floating Bin(GA) Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
GA	120	144	_	
GB	144	173		
GC	173	208	mcd	I _F =10mA
GD	208	250	_	
GE	250	300		

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
G1	513.0	516.0		
G2	516.0	519.0	_	I _F =10mA
G3	519.0	522.0	-	
G4	522.0	525.0	- nm	
G5	525.0	528.0		
G6	528.0	531.0		

Bin Range of Dominant Voltage

Bin Code	Min.	Max.	Unit	Condition
G1	2.5	3.7	V	I _F =10mA

Note:

1. Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

Floating Bin(BD) Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
BA	20	24		I _F =10mA
BB	24	29	_	
BC	29	35	- - mod	
BD	35	42	– mcd	
BE	42	50		
BF	50	60		

Bin Range of Dominant Wavelength

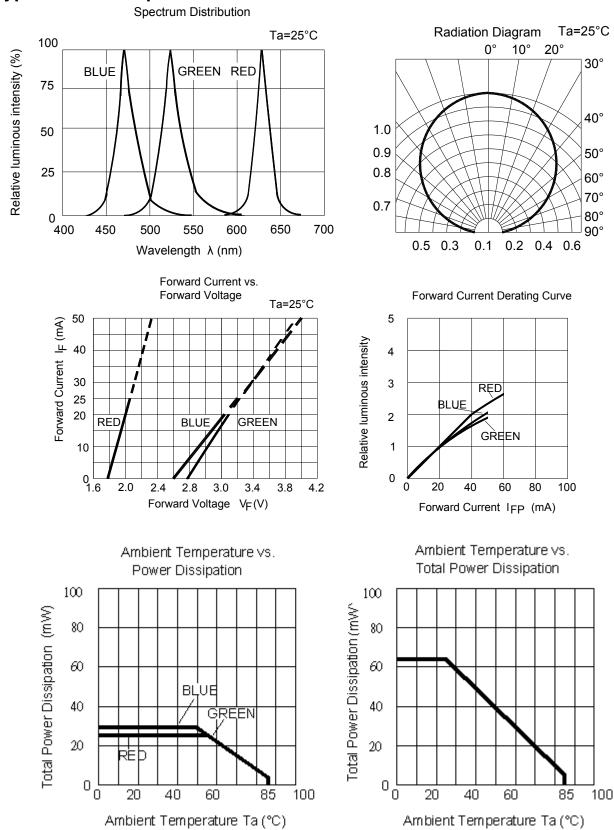
Bin Code	Min.	Max.	Unit	Condition
B1	461.0	464.0		
B2	464.0	467.0	_	
B3	467.0	470.0	nm	I _F =10mA
B4	470.0	473.0	_	
B5	473.0	476.0		

Bin Range of Dominant Voltage

Bin Code	Min.	Max.	Unit	Condition
B1	2.5	3.7	V	I _F =10mA

Note:

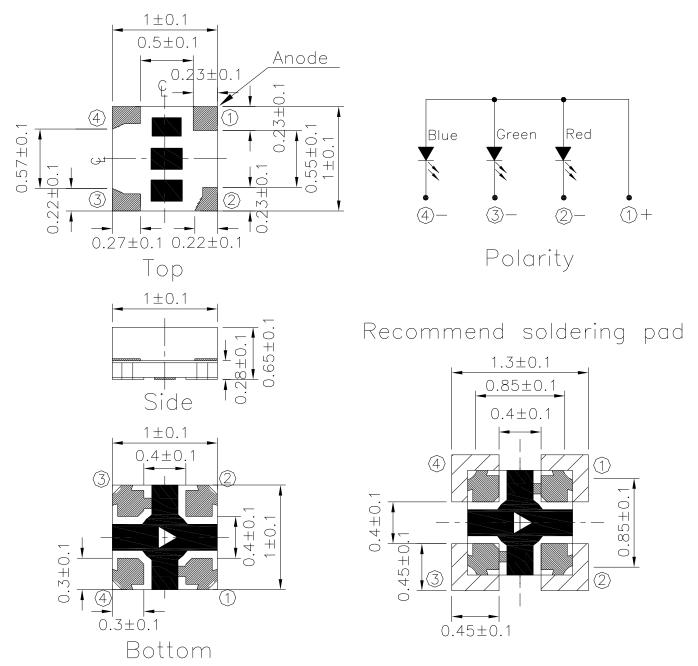
- 1. Tolerance of Luminous Intensity: ±10%
- 2. Tolerance of Dominant Wavelength: ±1nm



Typical Electro-Optical Characteristics Curves

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Package Dimension

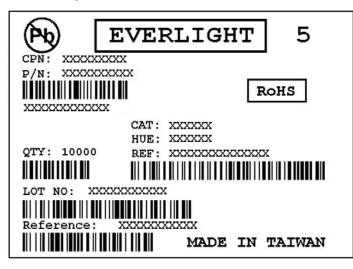


Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm

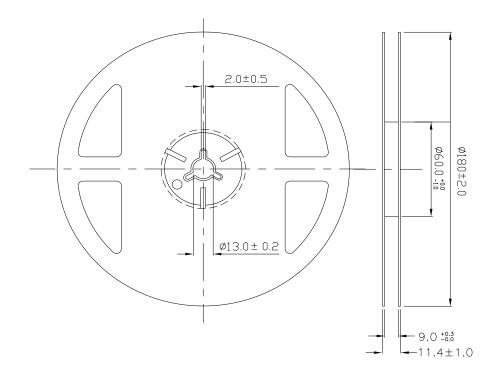
Moisture Resistant Packing Materials

Label Explanation



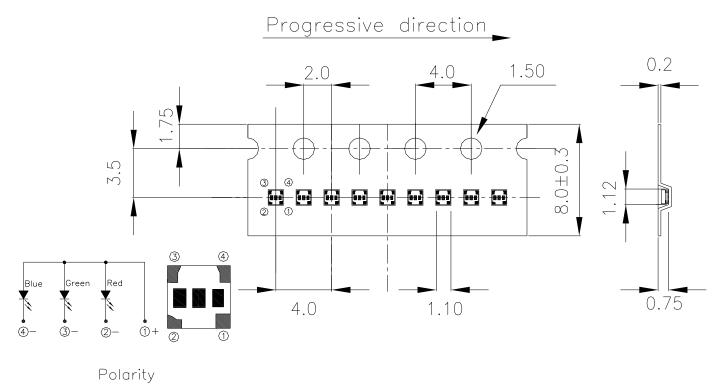
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions



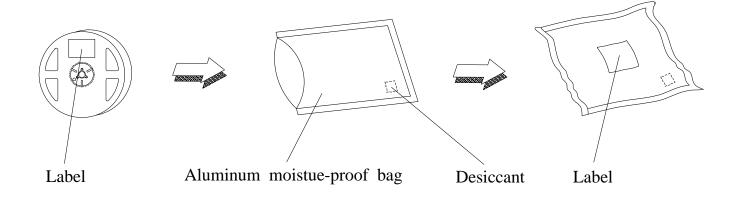
Carrier Tape Dimensions:

The minimum quantity of packing is 10000 pcs per reel. The rest quantity which could not reach 10000 pcs per reel will goes to 4000 pcs per reel.



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

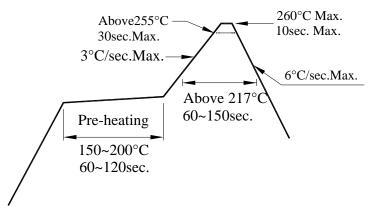
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Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 168Hrs under 30° C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5℃ for 24 hours.
 - 2.5 Before using LEDs, baking treatment should be implemented based on the following conditions: pre-curing at $60\pm5^{\circ}$ C for 24 hours or $125\pm5^{\circ}$ C for 3 hours.
- 3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

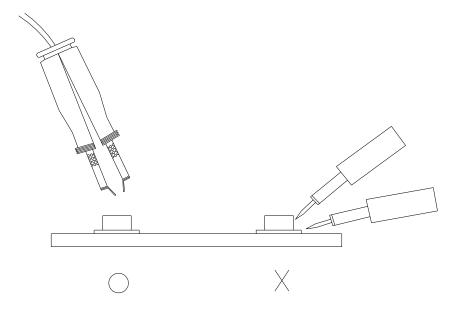
4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

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5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



6.Directions for use

The LEDs should be operated with forward bias. The driving circuit must be designed so that the LEDs are not subjected to forward or reverse voltage while it is off. If reverse voltage is continuously applied to the LEDs, It may cause migration resulting in LED damage.

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